



Product Change Notification / MFOL-12SBEE528

Date:

28-Oct-2022

Product Category:

PON ONU/OLT Devices, SAS Silicon & SW, SONET/SDH/T1/E1 Devices

PCN Type:

Manufacturing Change

Notification Subject:

CCB 5284 Final Notice: Qualification of GX92 as a new substrate material for PM8005C-F3EI, PM8004C-F3EI, XYRPM8005C-F3EI, XYRPM8004C-F3EI, PAS5211A-F3EI, and PM5369-FEI catalog part numbers (CPN) available in 592L BGA (27x27x2.24mm), 896L BGA (31x31x2.24mm), and 672L BBGA (27x27x3.32mm) packages assembled at STAK assembly site.

Affected CPNs:

[MFOL-12SBEE528_Affected_CPN_10282022.pdf](#)

[MFOL-12SBEE528_Affected_CPN_10282022.csv](#)

Notification Text:

PCN Status:Final Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of GX92 as a new substrate material for PM8005C-F3EI, PM8004C-F3EI, XYRPM8005C-F3EI, XYRPM8004C-F3EI, PAS5211A-F3EI, and PM5369-FEI catalog part numbers (CPN) available in 592L BGA (27x27x2.24mm), 896L BGA (31x31x2.24mm), and 672L BBGA (27x27x3.32mm) packages assembled at STAK assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	STATS CHIPAC KOREA LTD. (STAK)	STATS CHIPAC KOREA LTD. (STAK)
Die Attach Material	WF6317	WF6317
Underfill material	U8410-73C	U8410-73C
Solder Ball	SAC305	SAC305
Substrate Material	GX3	GX92

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve manufacturability by qualifying GX92 as a new substrate material.

Change Implementation Status:In Progress

Estimated First Ship Date:November 20, 2022 (date code: 2248)

Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2022					November 2022			
	41	42	43	44	45	46	47	48	49
Workweek									
Qual Report Availability				X					
Final PCN Issue Date				X					
Estimated Implementation Date								X	

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:October 28, 2022: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_MFOL-12SBEE528_Qual Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PM8005C-F3EI

PM8004C-F3EI

XYRPM8005C-F3EI

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PM5369-FEI

PAS5211A-F3EI